We claim:

1. A composition comprising:

(a) 40 to 60 wt.% of an alkylbenzene sulfonic acid; and

(b) 40 to 60 wt.% of an alkanolamide, an ethoxylated alkanolamide, an alkanolamine, or an ethoxylated amine;

said wt.% amounts based on the combined amounts of (a) and (b);

wherein the composition is a non-aqueous solder flux.

2. The composition of claim **1** wherein the alkyl group of the alkylbenzene sulfonic acid is a linear or branched C_1-C_{18} alkyl group.

3. The composition of claim **1** wherein the alkylbenzene sulfonic acid is dodecylbenzene sulfonic acid.

4. The composition of claim **1** wherein the composition comprises the alkylbenzene sulfonic acid and an ethoxylated amine.

5. The composition of claim **4** wherein the ethoxylated amine is a cocamine ethoxylate, a lauramine ethoxylate, or a tallowamine ethoxylate, each having an average of 2 to 5 EO units.

6. The composition of claim **4** wherein the alkylbenzene sulfonic acid is dodecylbenzene sulfonic acid and the ethoxylated amine is a tallowamine ethoxylate having an average of 2 to 5 EO units.

7. The composition of claim **1** comprising 45 to 55 wt.% of the alkylbenzene sulfonic acid and 45 to 55 wt.% of an ethoxylated amine.

8. The composition of claim **1** wherein the alkanolamide is cocamide MEA, cocamide DEA, lauramide MEA, lauramide DEA, oleamide MEA, oleamide DEA, cocamide MIPA, lauramide MIPA, or oleamide MIPA.

9. The composition of claim **1** wherein the ethoxylated alkanolamide is a PEG cocamide or a PEG lauramide, either having an average of 4 to 8 EO units.

10. The composition of claim **1** wherein the alkanolamine is diethanolamine.

11. The composition of claim **1** wherein the composition is essentially free of fatty acid salts.

12. The composition of claim **1** wherein the composition has good wettability on metal coupons in a wetting balance test as described herein compared with that of a

control flux as evidenced by a wetting force that is generated within 1 second from the start of the test, and is sustained for at least 10 seconds, of greater than 0.2 mN/mm.

13. The composition of claim **1**, that upon dilution with water, has a pH within the range of 1.0 to 6.0.

14. A mixture comprising solder and the composition of claim **1**.

15. A composition comprising:

(a) 40 to 60 wt.% of an acidic phosphate ester; and

(b) 40 to 60 wt.% of an alkanolamide, an ethoxylated alkanolamide, an alkanolamine, or an ethoxylated amine;

said wt.% amounts based on the combined amounts of (a) and (b);

wherein the composition is a non-aqueous solder flux.

16. The composition of claim **15** wherein the acidic phosphate ester is a phosphate ester of an ethoxylated isodecyl alcohol, an ethoxylated tridecyl alcohol, an ethoxylated tristyrylphenol, or an ethoxylated nonylphenol.

17. The composition of claim **15** comprising the acidic phosphate ester and an alkanolamide, an ethoxylated alkanolamide, or an ethoxylated amine.

18. The composition of claim **17** wherein the ethoxylated amine is a cocamine ethoxylate, a lauramine ethoxylate, or a tallowamine ethoxylate, each having an average of 2 to 5 EO units.

19. The composition of claim **17** wherein the alkanolamide is cocamide MEA, cocamide DEA, lauramide MEA, lauramide DEA, oleamide MEA, oleamide DEA, cocamide MIPA, lauramide MIPA, or oleamide MIPA.

20. The composition of claim **17** wherein the ethoxylated alkanolamide is a PEG cocamide or a PEG lauramide, either having an average of 4 to 8 EO units.

21. The composition of claim **15** comprising the acidic phosphate ester and an alkanolamine.

22. The composition of claim **21** wherein the alkanolamine is diethanolamine.

23. The composition of claim **15** wherein the composition has good wettability on metal coupons in a wetting balance test as described herein compared with that of a control flux as evidenced by a wetting force that is generated within 1 second from the start of the test, and is sustained for at least 10 seconds, of greater than 0.2 mN/mm.

24. The composition of claim **15**, that upon dilution with water, has a pH within the range of 1.0 to 6.0.

25. A mixture comprising solder and the composition of claim **15**.

26. A composition consisting essentially of:

(a) 40 to 60 wt.% of an alkylbenzene sulfonic acid or an acidic phosphate ester; and

(b) 40 to 60 wt.% of an alkanolamide, an ethoxylated alkanolamide, an alkanolamine, or an ethoxylated amine;

said wt.% amounts based on the combined amounts of (a) and (b);

wherein the composition is a non-aqueous solder flux.

27. The composition of claim **26** wherein the alkyl group of the alkylbenzene sulfonic acid is a linear or branched C_1-C_{18} alkyl group.

28. The composition of claim **26** wherein the acidic phosphate ester is a phosphate ester of an ethoxylated isodecyl alcohol, an ethoxylated tridecyl alcohol, an ethoxylated tristyrylphenol, or an ethoxylated nonylphenol.

29. The composition of claim **26** wherein the alkanolamide is cocamide MEA, cocamide DEA, lauramide MEA, lauramide DEA, oleamide MEA, oleamide DEA, cocamide MIPA, lauramide MIPA, or oleamide MIPA.

30. The composition of claim **26** consisting essentially of 45 to 55 wt.% of the alkylbenzene sulfonic acid or acidic phosphate ester and 45 to 55 wt.% of the alkanolamide, ethoxylated alkanolamide, alkanolamine, or ethoxylated amine.

31. A mixture comprising solder and the composition of claim **26**.

32. A method of making a solder flux composition, the method comprising: (a) combining 40 to 60 wt.% of an alkylbenzene sulfonic acid or an acidic phosphate ester with 40 to 60 wt.% of an alkanolamide, an ethoxylated alkanolamide, an alkanolamine, or an ethoxylated amine, and (b) mixing until the composition is substantially homogeneous.

33. A method which comprises using the composition of claim **1** as a component of a tacky solder flux.